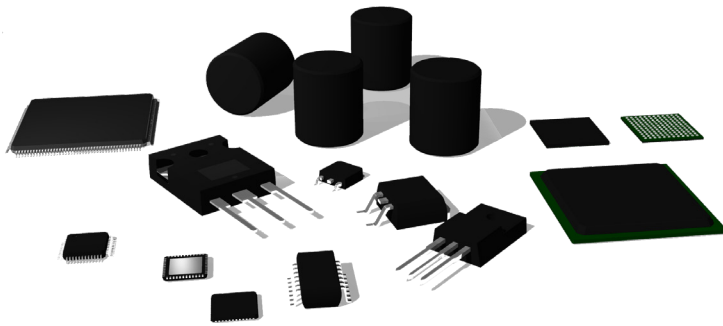


# High Tg Epoxy Moulding Compound



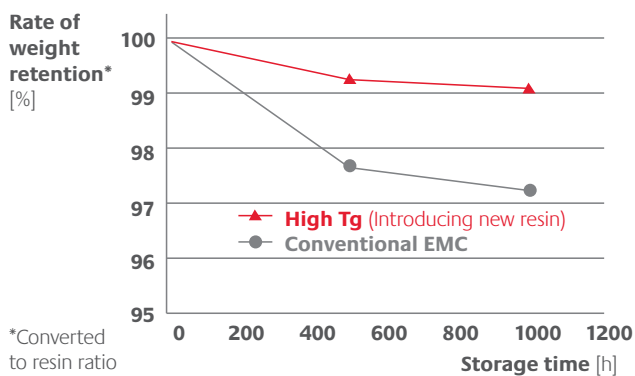
## APPLICATIONS

- ▶ Power module devices
  - Electrical railway
  - Equipment for industry
  - Automotive
- ▶ Power discrete

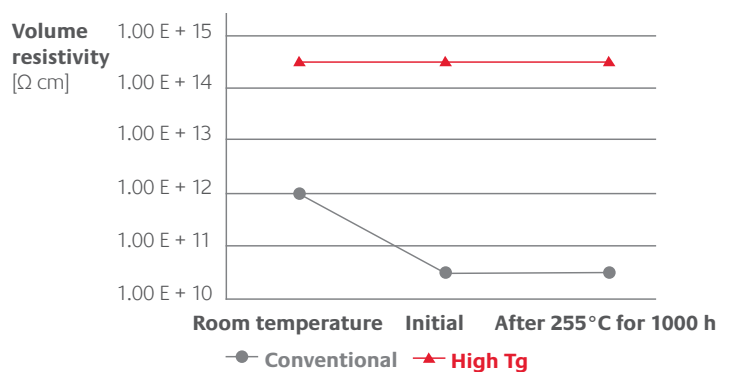
## FEATURES

- ▶ Excellent heat resistance
  - Tg ~ 250°C
  - Lower weight loss at high temperature storage (HTS)
- ▶ Excellent dimensional stability
- ▶ High electric resistivity at higher temperature
- ▶ Good resistance against oil

## Weight loss at HTS (200°C)



## Electric resistivity (200°C)



## General properties

Item	Unit	XKE-G8393
Spiral flow (175°C)	cm	165
Gel time	s	45
Flow viscosity	Pa * s	9
CTE α 1	ppm/°C	10
CTE α 2	ppm/°C	50
Tg	°C	250